

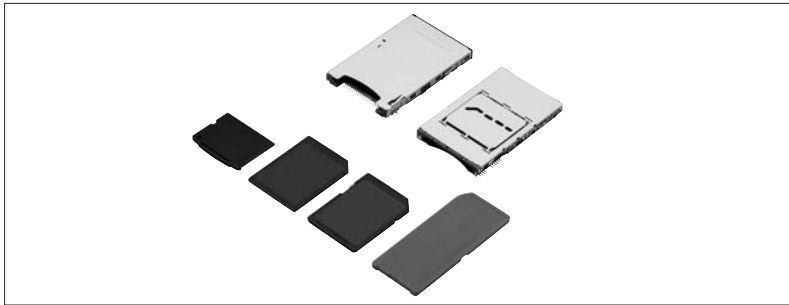
Combine Type Connector (for SD Memory Card, MultiMediaCard™, Memory Stick™, xD-Picture Card™)

SCDE Series



Push-in push-out eject mechanism applicable to four media types.

- For SD Memory Card
- For microSD™ Card
- For SIM Card 8pins
- For W-SIM



- For Memory Stick Micro™
- For Memory Stick™
- Combine Type

- For Compact Flash™
- For PC cards supporting CardBus
- For Express Card™
- For CMOS Camera Module

Features

- Applicable to four memory card standards - SD Memory Card, MultiMediaCard™, Memory Stick™ and xD-Picture Card™.
- Push-push ejection mechanism applied in both card types.
- Same insertion and ejection position applied for both cards.

Applications

- For desktop PCs, notebook PCs, various personal digital assistants, digital still cameras, digital camcorders, facsimile machines and printers.
- For home audio equipment (TVs and set top boxes)
- For audio systems
- For headphone players

Typical Specifications

Items		Specifications	
Structure	Applicable media	SD Memory Card	
		MultiMediaCard™	
		Memory Stick™	
		xD-Picture Card™	
	Mounting type	Surface mounting type	
Mounting style	Standard mount / Reverse mount		
Media ejection structure	Push-push type		
Performance	Operating temperature range	-10°C to +60°C	
	Voltage proof	500V AC 1minute (SCDE1), 250V AC 1minute (SCDE2)	
	Insulation resistance (Initial)	1,000MΩ min.	
	Contact resistance (Initial)	Connector contacts	100mΩ max. (SCDE1), 150mΩ max. (SCDE2)
		Detection switch	500mΩ max. (SCDE1), 600mΩ max. (SCDE2)
Insertion and removal cycle	10,000cycles (SD Memory Card, xD-Picture Card™) 12,000cycles (Memory Stick™)		

Product Line

Media ejection structure	Mounting system	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	0	Tray	SCDE1C0200	1
	Reverse mount			SCDE2B0100	2



Dimensions

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
1		
2	<p>On the card entry side, the metal exposed part is connected to terminal No.9 of the xD card.</p>	

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For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

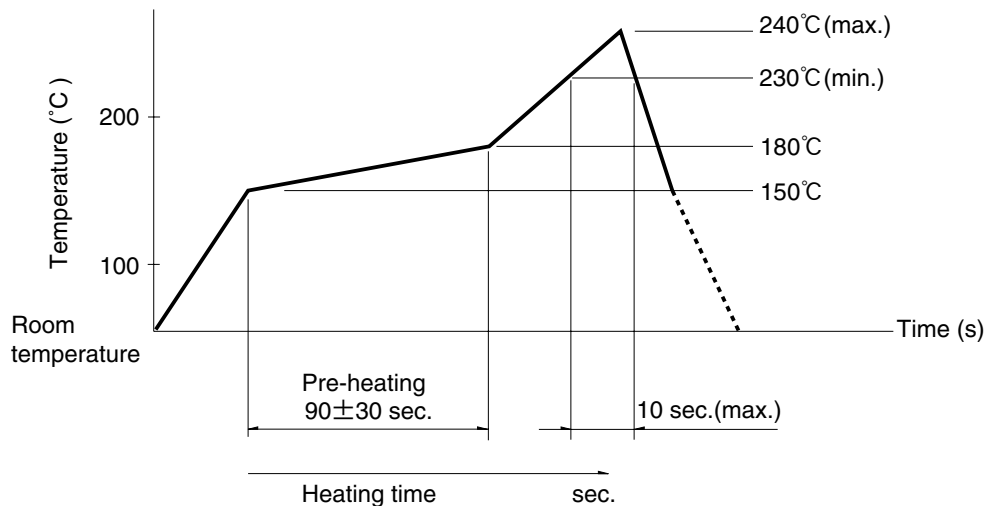
For Express Card™

For CMOS Camera Module

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

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